



PATENT

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Ayesha S. Wilks

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Vishnu K. Agarwal

Attorney Docket No.: 501082.16 (98-0616)

Serial No. : 09/652,580

Group Art Unit : 2825

Filed

: August 31, 2000

Examiner

: Caridad M. Everhart

Title

: DEVICE AND METHOD FOR PROTECTING AGAINST OXIDATION OF A

CONDUCTIVE LAYER IN SAID DEVICE

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner of Patents Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. §§ 1.56 and 1.97 through 1.98, applicant wishes to make known to the Patent and Trademark Office the references set forth on the attached form PTO-1449 (copies of the cited references, as required under 37 C.F.R. § 1.98, are enclosed). Although the aforesaid references are made known to the Patent and Trademark Office in compliance with applicant's duty to disclose all information he is aware of which is believed relevant to the examination of the above-identified application, applicant believes that his invention is patentable.

I hereby certify that no item set forth on the attached form PTO-1449 was cited in a communication from a foreign patent office in a counterpart foreign application or, to my knowledge, after making reasonable inquiry, was known to any individual designated in 37 C.F.R. § 1.56(c) more than three months prior to the filing of this Supplemental Information Disclosure Statement.

Please acknowledge receipt of this Supplemental Information Disclosure Statement and kindly make the cited references of record in the above-identified application.

Respectfully submitted

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Paul F. Rusyn

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PFR:asw

Enclosures:

Postcard Form PTO-1449 Cited References (4)

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